

# MOS FIELD EFFECT TRANSISTOR $\mu PA1874$

# N-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

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# DESCRIPTION

The  $\mu$ PA1874 is a switching device which can be driven directly by a 2.5-V power source.

This device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

# FEATURES

- 2.5-V drive available
- Low on-state resistance
- $\begin{array}{l} R_{DS(on)1} = 14.0 \ m\Omega \ MAX. \ (V_{GS} = 4.5 \ V, \ I_{D} = 4.0 \ A) \\ R_{DS(on)2} = 14.5 \ m\Omega \ MAX. \ (V_{GS} = 4.0 \ V, \ I_{D} = 4.0 \ A) \\ R_{DS(on)3} = 16.5 \ m\Omega \ MAX. \ (V_{GS} = 3.1 \ V, \ I_{D} = 4.0 \ A) \\ R_{DS(on)4} = 19.5 \ m\Omega \ MAX. \ (V_{GS} = 2.5 \ V, \ I_{D} = 4.0 \ A) \\ \end{array}$
- Built-in G-S protection diode against ESD

## **ORDERING INFORMATION**

PART NUMBER	PACKAGE
$\mu$ PA1874GR-9JG	Power TSSOP8

# ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Drain to Source Voltage ( $V_{GS} = 0 V$ )	VDSS	30
Gate to Source Voltage ( $V_{DS} = 0 V$ )	Vgss	±12
Drain Current (DC) (T <sub>A</sub> = 25°C)	D(DC)	±8.0
Drain Current (pulse) <sup>Note 1</sup>	D(pulse)	±80
Total Power Dissipation (2 unit) Note 2	P⊤	2.0
Channel Temperature	Tch	150
Storage Temperature	Tstg	–55 to +150

## **Notes 1.** PW $\leq$ 10 $\mu$ s, Duty Cycle $\leq$ 1%

- 2. Mounted on ceramic substrate of 5000 mm<sup>2</sup> x 1.1 mm
- **Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

V

V A

A W

°C

°C

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# PACKAGE DRAWING (Unit: mm)

1.2 MAX.

- 1.0±0.05

:Drain1

:Gate1

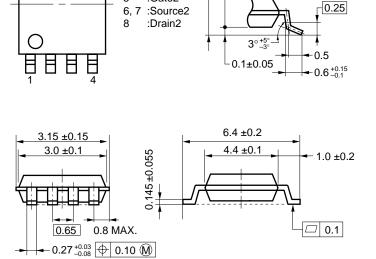
:Gate2

2, 3 :Source1

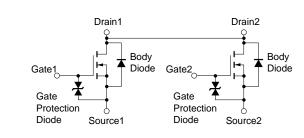
1

4

5



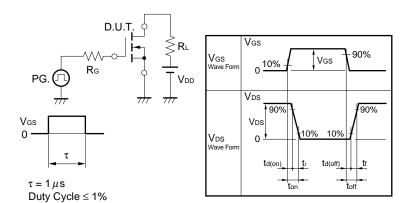
## **EQUIVALENT CIRCUIT**



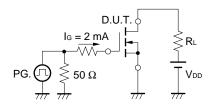
# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	Vds = 30 V, Vgs = 0 V			10	μA
Gate Leakage Current	lgss	V <sub>GS</sub> = ±12 V, V <sub>DS</sub> = 0 V			±10	μA
Gate Cut-off Voltage	$V_{GS(off)}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.0 mA	0.5	1.0	1.5	V
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4.0 A	5.0			S
Drain to Source On-state Resistance	RDS(on)1	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.0 A	9.0	11.0	14.0	mΩ
	RDS(on)2	V <sub>GS</sub> = 4.0 V, I <sub>D</sub> = 4.0 A	9.5	11.5	14.5	mΩ
	RDS(on)3	V <sub>GS</sub> = 3.1 V, I <sub>D</sub> = 4.0 A	10.0	12.5	16.5	mΩ
	RDS(on)4	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 4.0 A	11.0	14.5	19.5	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		1280		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		260		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		170		pF
Turn-on Delay Time	td(on)	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 4.0 A		70		ns
Rise Time	tr	V <sub>GS</sub> = 4.0 V		310		ns
Turn-off Delay Time	td(off)	R <sub>G</sub> = 10 Ω		440		ns
Fall Time	tr			410		ns
Total Gate Charge	QG	V <sub>DD</sub> = 24 V		14		nC
Gate to Source Charge	QGS	V <sub>GS</sub> = 4.0 V		2.0		nC
Gate to Drain Charge	Qgd	I <sub>D</sub> = 8.0 A		7.0		nC
Diode Forward Voltage	VF(S-D)	IF = 8.0 A, VGS = 0 V		0.81		V
Reverse Recovery Time	trr	IF = 8.0 A, VGS = 0 V		290		ns
Reverse Recovery Charge	Qrr	di/dt = 50 A/ μs		310		nC

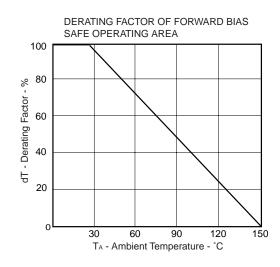
### **TEST CIRCUIT 1 SWITCHING TIME**



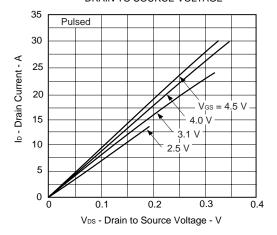
### **TEST CIRCUIT 2 GATE CHARGE**

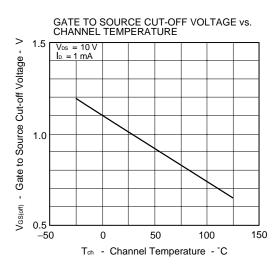


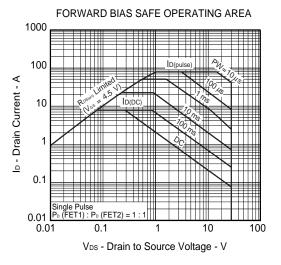
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)



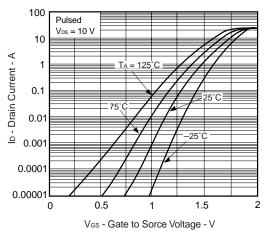




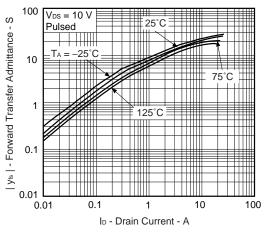




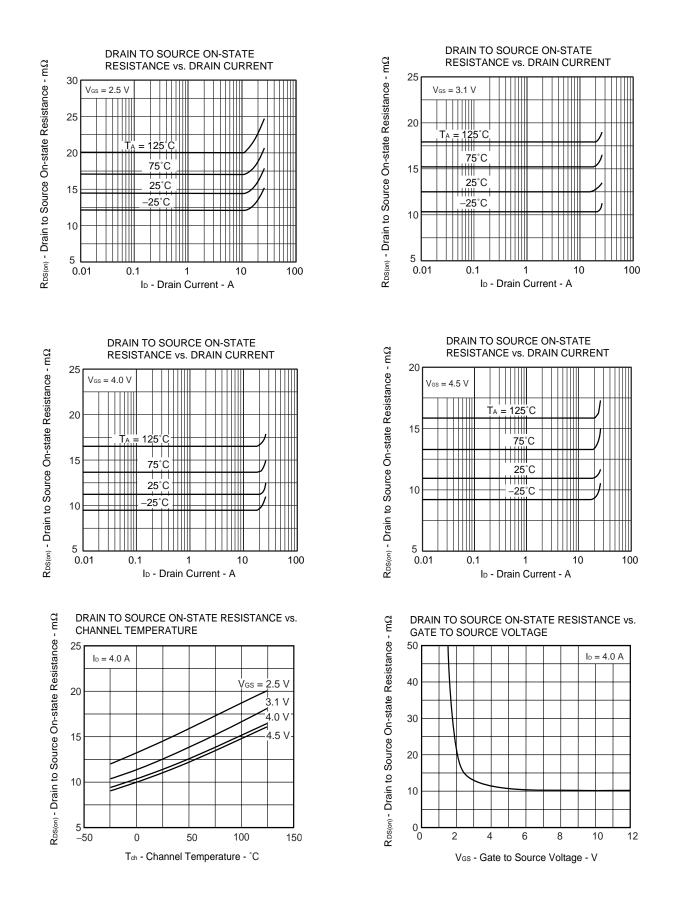
FORWARD TRANSFER CHARACTERISTICS



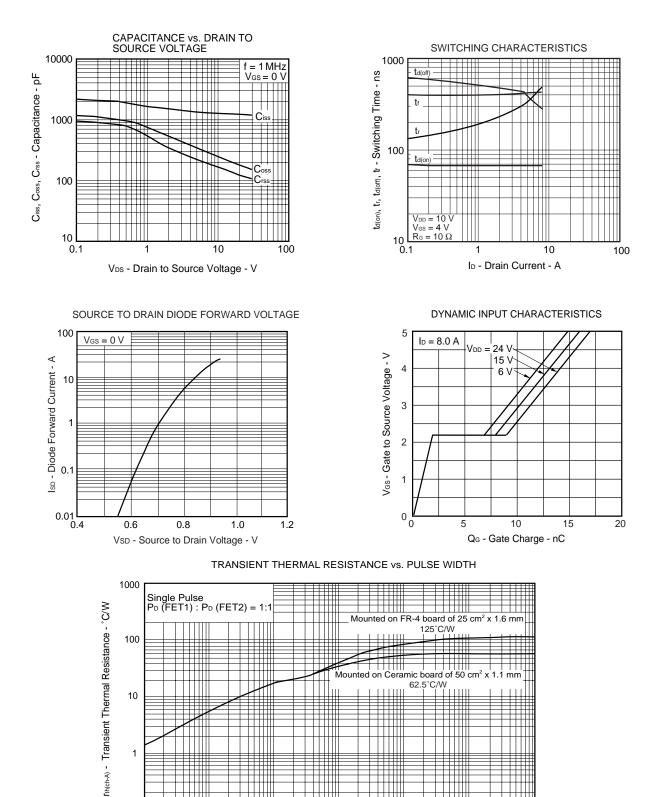
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



Data Sheet G15631EJ1V0DS



Data Sheet G15631EJ1V0DS



Data Sheet G15631EJ1V0DS

1 PW - Pulse Width - s 10

100

1000

1

0.1 0.001 0.01

0.1

5

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